



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL21B182KBANNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 1.8nF, 50V, ±10%, X7R, 0805

A. Samsung Part Number

<u>CL</u> <u>21</u> <u>B</u> <u>182</u> <u>K</u> <u>B</u> <u>A</u> <u>N</u> <u>N</u> <u>N</u> <u>O</u> ① ② ③ ④ ⑤ ⑥ ⑦ 8 ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor								
2	Size	0805 (inch c	ode)	L: 2.0	± 0.1	mm	W:	1.25	± 0.1	mm
3	Dielectric	X7R		8	Inner e	lectrode		Ni		
4	Capacitance	1.8 nF			Termin	ation		Cu		
(5)	Capacitance	±10 %			Plating			Sn 10	0%	(Pb Free)
	tolerance			9	Produc	t		Norma	al	
6	Rated Voltage	50 V		10	Special	l		Reser	ved for	future use
7	Thickness	0.65 ± 0.1	mm	11)	Packag	ing		Cardb	oard T	ype, 7"reel(4,000ea)

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition					
Capacitance	Within specified tolerance	1kHz±10% 1.0±0.2Vrms					
Tan δ (DF)	0.025 max.						
Insulation	More than 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.					
Resistance							
Appearance	No abnormal exterior appearance	Visual inspection					
Withstanding	No dielectric breakdown or	250% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	X7R						
Characteristics	(From -55℃ to 125℃, Capacitance change should be within ±15%)						
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)					
		with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating : 80~120 ℃ for 10~30sec.)					
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.					
Soldering heat	Tan δ, IR : initial spec.						

	Performance	Test condition				
Vibration Test	Capacitance change: within ±5%	Amplitude : 1.5mm				
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)				
		2hours × 3 direction (x, y, z)				
Moisture	Capacitance change: within ±12.5%	With rated voltage				
Resistance	Tan δ : 0.05 max	40±2℃, 90~95%RH, 500+12/-0 hour				
	IR : More than 25MΩ· <i>μ</i> F					
High Temperature	Capacitance change: within ±12.5%	With 200% of the rated voltage				
Resistance	Tan δ : 0.05 max	Max. operating temperature				
	IR : More than 50MΩ·μF					
		1000+48/-0 hour				
Temperature	Capacitance change: within ±7.5%	1 cycle condition				
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25°C				
		→ Max. operating temperature → 25°C				
		5 cycles test				

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}\!\text{C}$, 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.